

Rogers Corporation was founded in 1832 and has over 60 years of experience as a global supplier of high performance RF materials.

Rogers Corporation is the world's leading manufacturer of high performance dielectrics, laminates and prepregs used in microwave and RF printed circuit and related applications in Aerospace & Defense, Wireless & Wireline (digital) Infrastructure, Automotive Radar Sensor, Satellite TV, Mobile Internet Device and High End Chip Scale Packaging.

Rogers is headquartered in Chandler, Arizona. Additional manufacturing, sales and technical service locations in North America, Europe and Asia enable Rogers to support our global customers at the local level.

Beyond recently expanded manufacturing capability, an extensive and growing product portfolio supports a wide array of application needs and environments. Rogers' application and technical service engineers are ready to assist in material selection, for design and PCB manufacturing phases of your product development process.

With unmatched industry expertise, Rogers Corporation continues to conceive and develop new material solutions for ever more challenging problems. For example, over the last several years Rogers Corporation introduced thermal management materials and continues to innovate to meet the needs for a range of emerging higher power applications. Our dedication to improving on electrical characterization capabilities, already best in class, enables us to anticipate questions and work collaboratively to push the material performance envelope.



## Join Our Technology Support Hub Today & Access Online Tools:

### Instructional Videos

- Fabricator Focused Learning Series
- Coonrod's Corner
- Webinars
- 5G Videos



### Technical Articles

- Extensive database of articles and whitepapers



### Tools

- Interactive Product Properties Tool
- Resonator Calculator
- Microwave Impedance Calculator
- Dk Calculator
- Conversion Calculator



Available for download



[rogerscorp.com/techub](http://rogerscorp.com/techub)



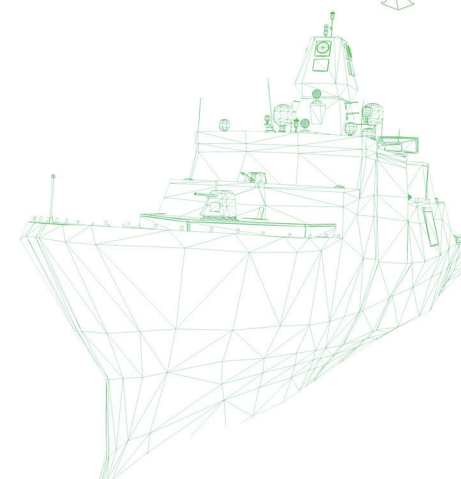
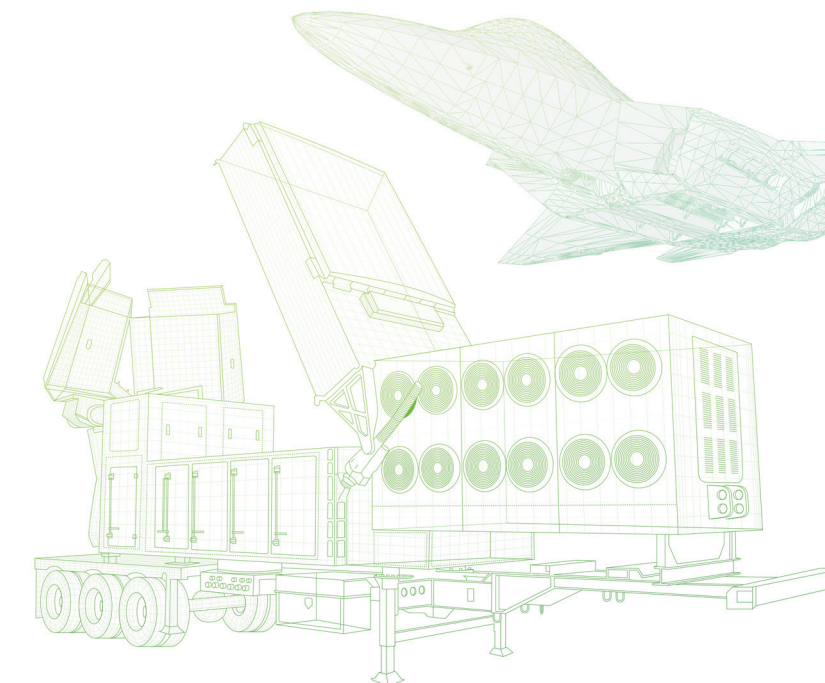
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# Engineered Material Solutions

**FOCUSED ON INNOVATION**



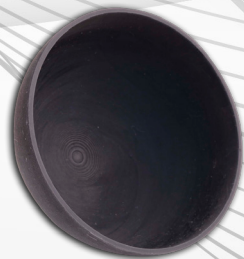
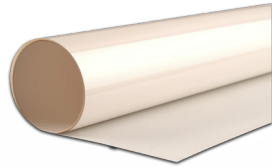
Leading your design challenges to the perfect solution



Advanced materials with high reliability under extreme conditions, critical for aerospace, commercial aircraft and defense applications.

For decades, design engineers have relied on Rogers' advanced materials to enable commercial aircraft and aerospace and defense systems, even in the harshest conditions. Today, our high reliability, high performance solutions can be found in the majority of the world's commercial and military aircraft. Look to Rogers for high frequency circuit materials for radar and navigation systems, ceramic substrates and laminated busbars that improve performance and dissipate heat, and gasketing solutions for extreme sealing and protection.

- Ultra Low Loss Laminates and Dielectrics
- High Thermally Conductive Materials
- Advanced Thermal Control Solutions
- Magnetodielectric Materials for Antenna Miniaturization
- Ablative and RF Transparent Materials for Radomes and Windows
- 3D Additive Manufacturing Low Loss, High Dk Resin Systems
- Advanced Phased Array Material Systems
- Formed and Shaped Dielectric Systems with Metallization Solutions



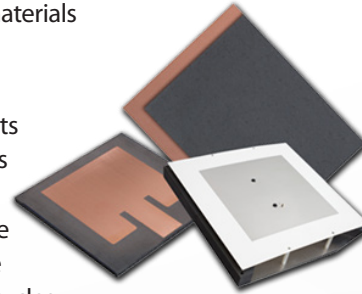
**FOR MORE DETAILED INFORMATION**

Scan the QR code to view our Product Selector Guide

## RF/HIGH RELIABILITY LAMINATES

Modern Aerospace and Defense systems rely on high performance and high reliability materials to achieve peak performance in demanding mission critical applications. Rogers is the leader in high reliability / high performance / high frequency PCB laminate solutions.

- RT/duroid® 5000 and RT/duroid 6000 product families
- RO3000®, CLTE™, CuClad®, DiClad® and IsoClad® PTFE based systems
- RO4000® thermoset systems, including RO4725JXR™, low Dk thermoset laminate, the lowest in the industry
- Cladding includes copper, and heavy metal backed options
- Compatible bondply and prepreg materials



## ANTENNA SOLUTIONS

Rogers' advanced material developments are leading performance enhancements to many antenna solutions. Rogers supports customers from the idea phase through production and have reference designs to accelerate customer design cycles.

- MAGTRES® Magnetodielectric System, enables miniaturization with 6x the bandwidth
- RT/duroid 5000 and RT/duroid 6000 PTFE systems
- RO3000, CLTE, CuClad, DiClad and IsoClad PTFE based systems
- RO4000 thermoset systems
- Radix™ 3D Printable Dielectric Systems

## ADVANCED MATERIALS

Rogers curamik® product suite offers best-in-class metallized ceramic substrates that enable higher power efficiency. Our curamik substrates consist of pure copper bonded or brazed to a ceramic substrate and are designed to carry higher currents, provide higher voltage isolation and operate over a wide temperature range.

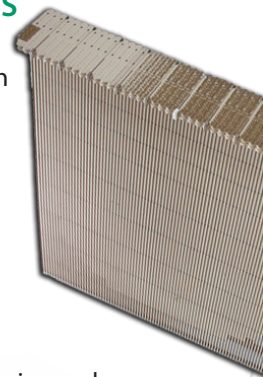
- DBC (Direct Bond Copper) available on AlN, Al2O3, HPS substrate circuit solutions
  - curamik Thermal
  - curamik Power
  - curamik Endurance
  - curamik Power Plus
- AMB (Active Metal Brazed) copper available on Si3N4 ceramic substrates
  - curamik Performance



## RADOME & RF TRANSPARENT WINDOWS

Rogers is the leading supplier of low loss PTFE materials used in RF Transparent windows and high performance Radome systems.

- Ablative solutions in high speed / high velocity systems
- Molded and shaped dielectric composites
- Metallized options available
- RF Transparent materials for use in Windows



## THERMAL MANAGEMENT

Thermal management is a critical element in the design and manufacturing of printed circuit boards (PCBs) for a wide range of applications. Quite simply, heat can be destructive. The more effectively heat is dissipated through and from a PCB, the better the opportunity for a long, reliable operating lifetime of that PCB.

- curamik micro-channel coolers
- COOLSPAN® Thermally and Electrically Conductive Adhesive (TECA)
- TC300™ and TC600™ series high thermal conductivity PTFE solutions
- RT/duroid 6035HTC and other high thermal conductivity solutions



## SPECIALTY DIELECTRICS

Rogers' specialty dielectrics include Radix 3D printable dielectrics and TMM® (Thermoset Microwave Material) moldable shaped thermoset materials.

- Radix 3D Printable dielectric expands design windows allowing unique spatially variant dielectric constant solutions such as Lenses and Radomes
- TMM systems with Dk ranges from ~3~13. Material is moldable and shapable into unique configurations for Radome, Windows and other high frequency applications
- Radix and TMM materials are compatible with various metallization solutions

